

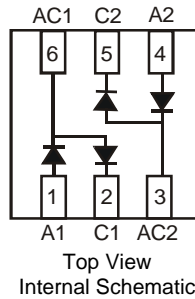
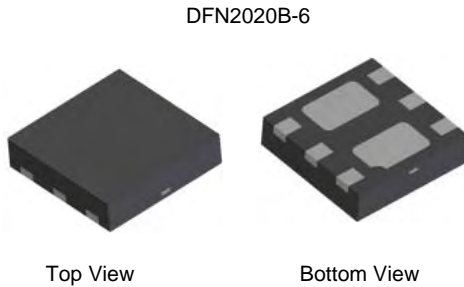
NEW PRODUCT

**Features**

- Fast Switching Speed
- Low Profile DFN Package (0.575mm typical thickness) is Much Thinner than Conventional SOT Style Packages
- Thermally Efficient DFN Package Features 500mW Power Dissipation Capability in a Compact 2.0 \* 2.0mm Footprint
- Two "BAV99" Circuits In One Package
- **Lead Free/RoHS Compliant (Note 1)**
- **"Green" Device (Note 2)**

**Mechanical Data**

- Case: DFN2020B-6
- Case Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: NiPdAu over Copper leadframe (Lead Free Plating). Solderable per MIL-STD-202, Method 208
- Polarity: See Diagram
- Weight: 0.006 grams (approximate)



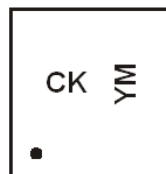
Pin 1 = A1 (anode 1, right below the notch indication)  
 Pin 2 = C1 (cathode 1)  
 Pin 3 = AC2 (internally connected to rectangular pad)  
 Pin 4 = A2 (anode 2)  
 Pin 5 = C2 (cathode 2)  
 Pin 6 = AC1 (internally connected to the pad with a notch)

**Ordering Information** (Note 3)

Part Number	Case	Packaging
BAV99BRLP-7	DFN2020B-6	3000/Tape & Reel

- Notes:
1. No purposefully added lead.
  2. Diodes Inc.'s "Green" policy can be found on our website at <http://www.diodes.com>.
  3. For packaging details, go to our website at <http://www.diodes.com>.

**Marking Information**



CK = Product Type Marking Code  
 YM = Date Code Marking  
 Y = Year (ex: Y = 2011)  
 M = Month (ex: 9 = September)

Date Code Key

Year	2011	2012	2013	2014	2015	2016	2017
Code	Y	Z	A	B	C	D	E

Month	Jan	Feb	Mar	Apr	May	Jun	Jul	Aug	Sep	Oct	Nov	Dec
Code	1	2	3	4	5	6	7	8	9	O	N	D

**Maximum Ratings** @ $T_A = 25^\circ\text{C}$  unless otherwise specified

Characteristic	Symbol	Value	Unit
Non-Repetitive Peak Reverse Voltage	$V_{RM}$	100	V
Peak Repetitive Reverse Voltage	$V_{RRM}$	75	V
Working Peak Reverse Voltage	$V_{RWM}$		
DC Blocking Voltage	$V_R$		
RMS Reverse Voltage	$V_{R(RMS)}$	53	V
Forward Continuous Current (Note 4)	$I_{FM}$	300	mA
Non-Repetitive Peak Forward Surge Current	$I_{FSM}$	@ $t = 1.0\mu\text{s}$	3.0
		@ $t = 1.0\text{ms}$	2.0
		@ $t = 1.0\text{s}$	0.5

**Thermal Characteristics**

Characteristic	Symbol	Value	Unit
Power Dissipation (Note 4)	$P_D$	500	mW
Thermal Resistance Junction to Ambient Air (Note 4)	$R_{\theta JA}$	250	$^\circ\text{C/W}$
Operating and Storage Temperature Range	$T_J, T_{STG}$	-65 to +150	$^\circ\text{C}$

**Electrical Characteristics** @ $T_A = 25^\circ\text{C}$  unless otherwise specified

Characteristic	Symbol	Min	Max	Unit	Test Condition
Reverse Breakdown Voltage (Note 5)	$V_{(BR)R}$	75	—	V	$I_R = 2.5\mu\text{A}$
Forward Voltage	$V_F$	—	0.715	V	$I_F = 1.0\text{mA}$
			0.855		$I_F = 10\text{mA}$
			1.0		$I_F = 50\text{mA}$
			1.25		$I_F = 150\text{mA}$
Reverse Current (Note 5)	$I_R$	—	2.5	$\mu\text{A}$	$V_R = 75\text{V}$
			50	$\mu\text{A}$	$V_R = 75\text{V}, T_J = 150^\circ\text{C}$
			30	$\mu\text{A}$	$V_R = 20\text{V}, T_J = 150^\circ\text{C}$
			25	nA	$V_R = 20\text{V}$
Total Capacitance	$C_T$	—	2.0	pF	$V_R = 0, f = 1.0\text{MHz}$
Reverse Recovery Time	$t_{rr}$	—	4.0	ns	$I_F = I_R = 10\text{mA}$ , $I_{rr} = 0.1 \times I_R, R_L = 100\Omega$

Notes: 4. Device mounted on FR-4 PCB, on minimum recommended, 2oz copper pad layout.  
5. Short duration pulse test used to minimize self-heating effect.

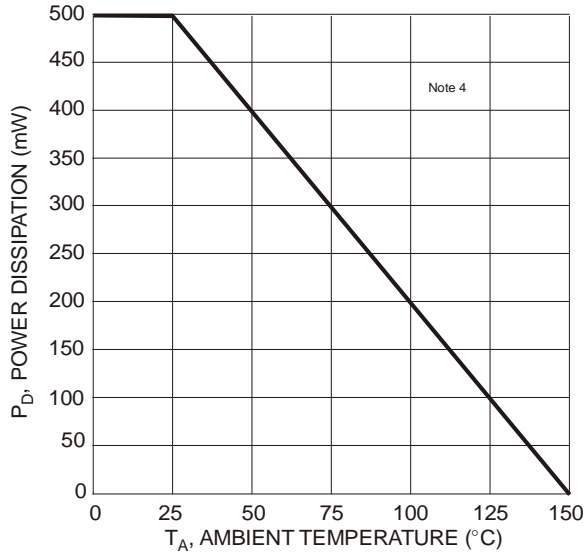


Fig. 1 Power Derating Curve, Total Package

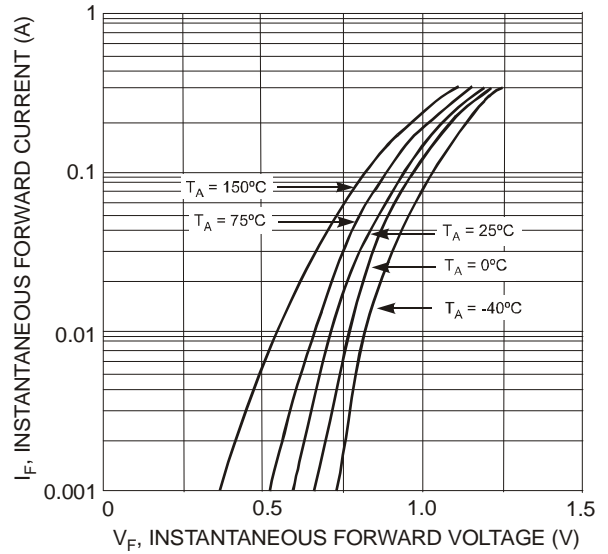


Fig. 2 Typical Forward Characteristics, Per Element

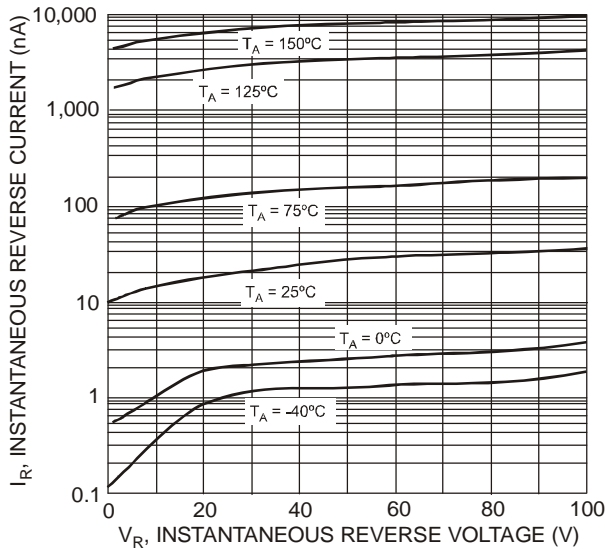


Fig. 3 Typical Reverse Characteristics, Per Element

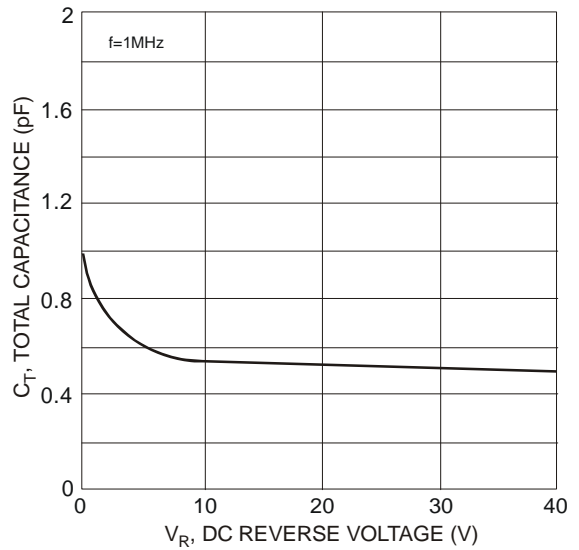
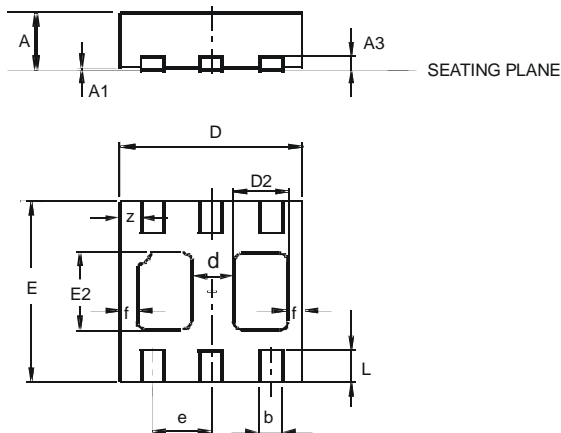


Fig. 4 Total Capacitance vs. Reverse Voltage, Per Element

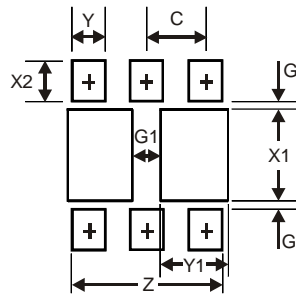
**Package Outline Dimensions**



Bottom View

DFN2020B-6			
Dim	Min	Max	Typ
A	0.545	0.605	0.575
A1	0	0.05	0.02
A3	—	—	0.13
b	0.20	0.30	0.25
D	1.95	2.075	2.00
d	—	—	0.45
D2	0.50	0.70	0.60
e	—	—	0.65
E	1.95	2.075	2.00
E2	0.90	1.10	1.00
f	—	—	0.15
L	0.25	0.35	0.30
z	—	—	0.225
All Dimensions in mm			

## Suggested Pad Layout



Dimensions	Value (in mm)
Z	1.67
G	0.20
G1	0.40
X1	1.0
X2	0.45
Y	0.37
Y1	0.70
C	0.65

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